

December 2013

FFB3904 / FMB3904 / MMPQ3904 NPN Multi-Chip General Purpose Amplifier

Description

This device is designed as a general-purpose amplifier and switch. The useful dynamic range extends to 100 mA as a switch and to 100 MHz as an amplifier. Sourced from Process 23.

Block Diagram



Figure 1. FFB3904 Device Package

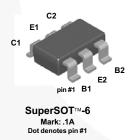


Figure 3. FMB3904 Device Package



Figure 5. MMPQ3904 Device Package

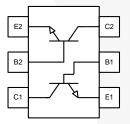


Figure 2. FFB3904 Internal Connection

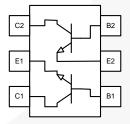


Figure 4. FMB3904 Internal Connection

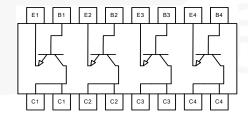


Figure 6. MMPQ3904 Internal Connection

Ordering Information

Part Number	Top Mark	Package	Packing Method
FFB3904	.1A	SC70 6L	Tape and Reel
FMB3904	.1A	SSOT 6L	Tape and Reel
MMPQ3904	MMPQ3904	SOIC 16L	Tape and Reel

Absolute Maximum Ratings(1)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}$ C unless otherwise noted.

Symbol	Parameter	Value	Unit
V _{CEO}	Collector-Emitter Voltage	40	V
V_{CBO}	Collector-Base Voltage	60	V
V_{EBO}	Emitter-Base Voltage	6.0	V
I _C	Collector Current - Continuous	200	mA
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Note:

1. These ratings are based on a maximum junction temperature of 150°C. These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty cycle operations.

Thermal Characteristics(2)

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol		Parameter	Max.			Unit	
		Farameter	FFB3904	FMB3904	MMPQ3904	Onit	
	D	Total Device Dissipation	300	700	1,000	mW	
	P_{D}	Derate above 25°C	2.4	5.6	8.0	mW/°C	
		Thermal Resistance, Junction to Ambient	415	180			
$R_{ heta JA}$		Thermal Resistance, Junction to Ambient, Effective 4 Die			125	°C/W	
	Thermal Resistance, Junction to Ambient, Each Die			240			

Note:

2. PCB size: FR-4 76 x 114 x 0.6T mm³ (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

Electrical Characteristics

Values are at $T_A = 25^{\circ}C$ unless otherwise noted.

Symbol	Par	ameter	Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics			•	l	•	
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage		I _C = 1.0 mA, I _B = 0	40			V
V _{(BR)CBO}	Collector-Base Br	reakdown Voltage	$I_C = 10 \mu A, I_E = 0$	60			V
V _{(BR)EBO}	Emitter-Base Bre	akdown Voltage	$I_E = 10 \mu A, I_C = 0$	6.0			V
I _{BL}	Base Cut-Off Cur	rent	$V_{CE} = 30 \text{ V}, V_{BE} = -3 \text{ V}$			50	nA
I _{CEX}	Collector Cut-Off	Current	$V_{CE} = 30 \text{ V}, V_{BE} = -3 \text{ V}$			50	nA
On Charac	cteristics ⁽³⁾			<u>'</u>			
		FFB3904, FMB3904	I _C = 0.1 mA, V _{CE} = 1.0 V	40			
		MMPQ3904		30			
		FFB3904, FMB3904	I _C = 1.0 mA, V _{CE} = 1.0 V	70			
h _{FE}	DC Current Gain	MMPQ3904		50			
		FFB3904, FMB3904	10 10 10	100		300	
		MMPQ3904	$I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$	75			
		All Devices	$I_C = 50 \text{ mA}, V_{CE} = 1.0 \text{ V}$	60			
		All Devices	I _C = 100 mA, V _{CE} = 1.0 V	30			
\	V _{CE} (sat) Collector-Emitter Saturation Voltage		I _C = 10 mA, I _B = 1.0 mA	1		0.2	
v _{CE} (sat)			I _C = 50 mA, I _B = 5.0 mA			0.3	V
\/ (4)	Base-Emitter Saturation Voltage		I _C = 10 mA, I _B = 1.0 mA	0.65		0.85	V
V _{BE} (sat)			I _C = 50 mA, I _B = 5.0 mA			0.95	V
Small-Sigr	nal Characteristic	s (MMPQ3904 only)					
f _T	Current Gain-Bandwidth Product		I _C = 10 mA, V _{CE} = 20 V, f = 100 MHz		250		MHz
C _{ob}	Output Capacitan	се	$V_{CB} = 5.0 \text{ V}, I_{E} = 0,$ f = 140 kHz		4.0		pF
C _{ib}	Input Capacitance	9	$V_{BE} = 0.5 \text{ V, I}_{C} = 0,$ f = 140 kHz		8.0		pF

Note:

3. Pulse test: pulse width \leq 300 μ s, duty cycle \leq 2.0%.

Typical Performance Characteristics

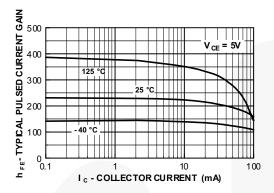


Figure 7. Typical Pulsed Current Gain vs. Collector Current

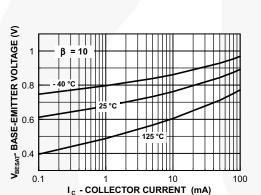


Figure 9. Base-Emitter Saturation Voltage vs. Collector Current

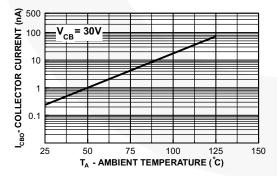


Figure 11. Collector Cut-Off Current vs. Ambient Temperature

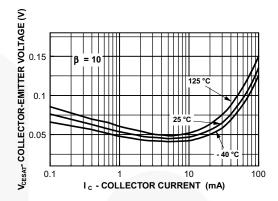


Figure 8. Collector-Emitter Saturation Voltage vs.
Collector Current

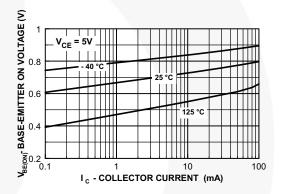


Figure 10. Base-Emitter On Voltage vs. Collector Current

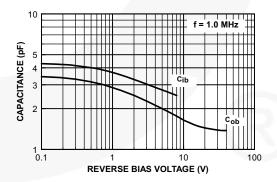


Figure 12. Capacitance vs. Reverse Bias Voltage

Typical Performance Characteristics (Continued)

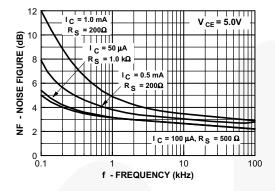


Figure 13. Noise Figure vs. Frequency

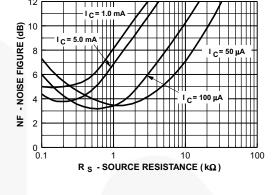


Figure 14. Noise Figure vs. Source Resistance

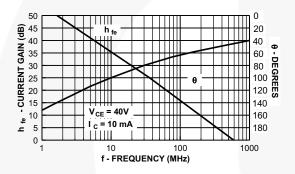


Figure 15. Current Gain and Phase Angle vs. Frequency

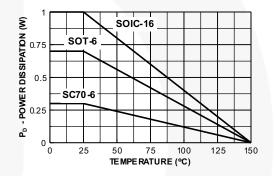


Figure 16. Power Dissipation vs. Ambient Temperature

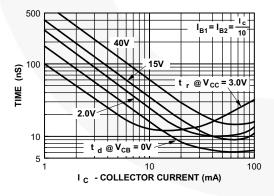


Figure 17. Turn-On Time vs. Collector Current

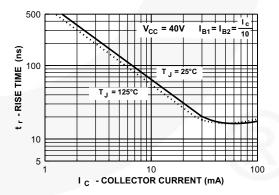


Figure 18. Rise Time vs. Collector Current

Typical Performance Characteristics (Continued)

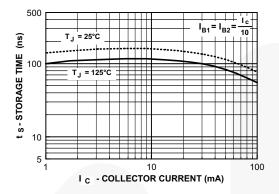


Figure 19. Storage Time vs. Collector Current

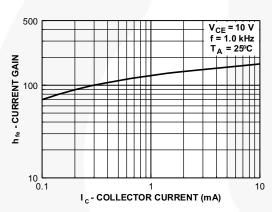


Figure 21. Current Gain

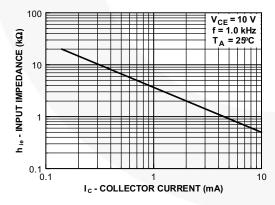


Figure 23. Input Impedance

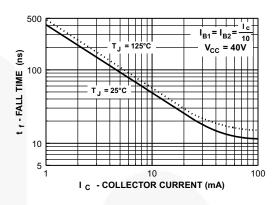


Figure 20. Fall Time vs. Collector Current

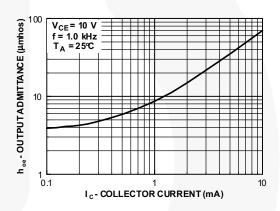


Figure 22. Output Admittance

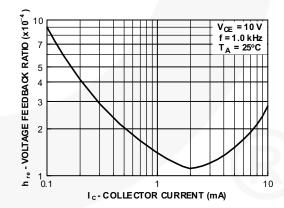


Figure 24. Voltage Feedback Ratio

Physical Dimensions

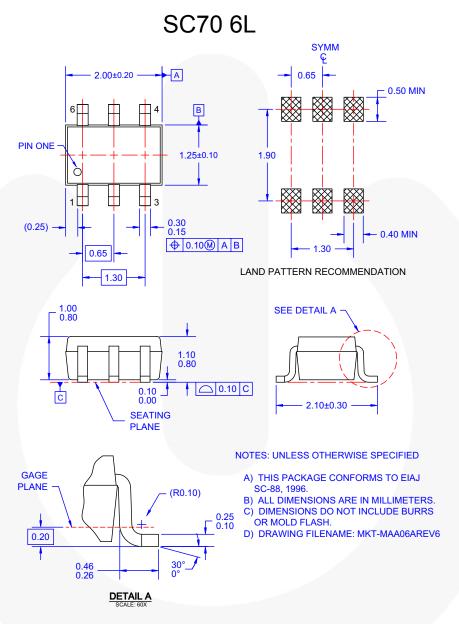


Figure 25. 6-LEAD, SC70, EIAJ SC-88, 1.25 MM WIDE (ACTIVE)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwq/MA/MAA06A.pdf.

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: http://www.fairchildsemi.com/packing_dwg/PKG-MAA06A.pdf.

Physical Dimensions (Continued)

SSOT 6L

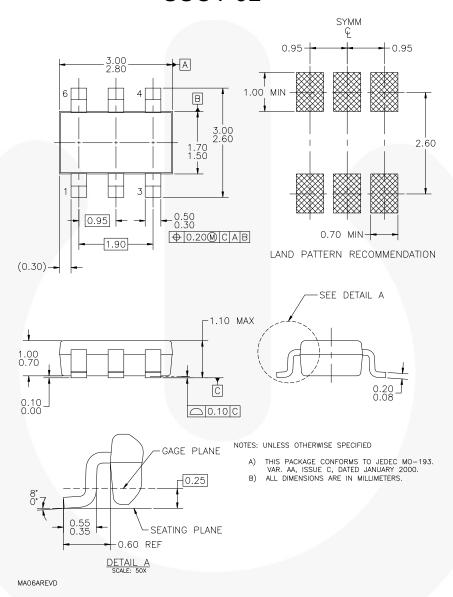


Figure 26. 6-LEAD, SUPERSOT-6, JEDEC MO-193, 1.6 MM WIDE (ACTIVE)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/MA/MA06A.pdf.

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: http://www.fairchildsemi.com/packing_dwg/PKG-MA06A.pdf.

Physical Dimensions (Continued)

SO 16L NB

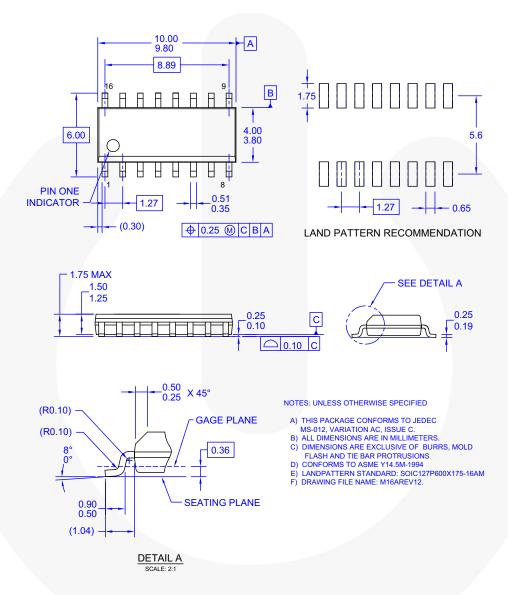


Figure 27. 16-LEAD, SOIC, JEDEC MS-012, 0.150 inch, NARROW BODY (ACTIVE)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/M1/M16A.pdf.

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: http://www.fairchildsemi.com/packing_dwg/PKG-M16A.pdf.





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ F-PFS™ AX-CAP®, **FRFET®** Global Power ResourceSM BitSiC™ Build it Now™ GreenBridge™ CorePLUS™ Green FPS™ CorePOWER™ Green FPS™ e-Series™ Gmax™ $CROSSVOLT^{\text{\tiny TM}}$ GTO™ $\mathsf{CTL}^{\scriptscriptstyle\mathsf{TM}}$ Current Transfer Logic™ IntelliMAX™

DEUXPEED® ISOPLANAR™

Dual Cool™ Making Small Speakers Sound Louder

EcoSPARK® and Better™

EfficientMax™ MegaBuck™

ESBC™ MICROCOUPLER™

MicroFET™

Tairchild® MicroPak™ MicroPak™
Fairchild Semiconductor® MillerDrive™
FACT Quiet Series™ MotionMax™
FACT® mWSaver®
FAST® OptoHiT™

FAST® mWSaver®
FastvCore™ OptoHiT™ OPTOLOGIC®
FETBench™ OPTOPLANAR®
FPS™

PowerTrench[®] PowerXS™

Programmable Active Droop™

QFET[®]
QS[™]
Quiet Series[™]
RapidConfigure[™]

Saving our world, 1mW/W/kW at a time™ SignalWise™

SmartMax[™] SMART START[™]

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™

Sync-LockTM
SYSTEM
GENERAL®*
TinyBoost®
TinyBuck®
TinyCalcTM
TinyLogic®
TINYOPTOTM
TinyPowerTM
TinyPWMTTM
TranSiCTM
Trault DetectTM
TRUECURRENT®*

µSerDesTM

SerDes"
UHC®
Ultra FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XS™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN, NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Definition of Terms				
Datasheet Identification	Product Status	Definition		
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.		
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.		
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.		
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.		

Rev. 166

^{*} Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Fairchild Semiconductor:

FFB3904 FFB3904_Q